



Fig. 3(b). The first half stages of the CMOS charge pump is constructed from the NMOS transistors ( $M_3, M_4$ ) and the back half stages are constructed from PMOS transistors ( $M_5, M_6$ ). This scheme ensures the maximum overdrive voltage can be provided to each transistor when gate is driven by high-voltage clocks ( $\phi$ ). The transistors  $M_1$  and  $M_2$  are still functional but most of the current flows through the CMOS switch ( $M_3, M_4$ ) because the on-resistance is much smaller than that of diode connected MOSFETs ( $M_1, M_2$ ). As a result, the CMOS charge pump improves the conversion efficiency while Dickson charge pump achieves low voltage startup.

IV. Measurement Results

The proposed circuit was designed and fabricated in 65nm CMOS process. Fig. 4 shows the chip micrograph with active area of  $0.78\text{mm}^2$ . Each pumping capacitor is 28.6pF and MIM capacitor is used.

The measured dependence of the output voltage and conversion efficiency on output power is shown in Fig. 5. The proposed charge pump successfully converts a 120mV input to 770mV output with the conversion efficiency of 38.8%. Table I compares the performance of fully-integrated charge pumps. Ref [3] and [4] achieve high conversion efficiency but the operation voltage is high. On the other hand, [5] achieves low voltage operation but the conversion efficiency is low. The proposed charge pump achieved the lowest operation voltage with moderate conversion efficiency.

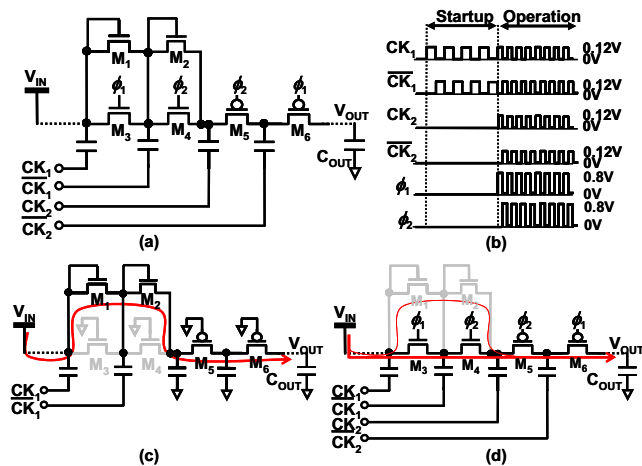


Fig.3. (a) Simplified circuit schematic and (b) operation sequences of the proposed dual-mode charge pump. (c) Startup mode and (d) Operation mode.

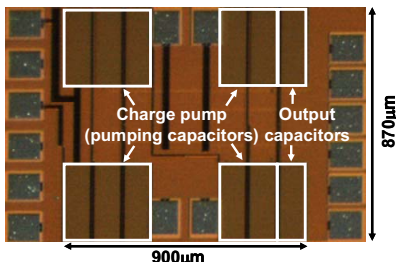


Fig.4. Chip micrograph of proposed dual-mode charge pump.

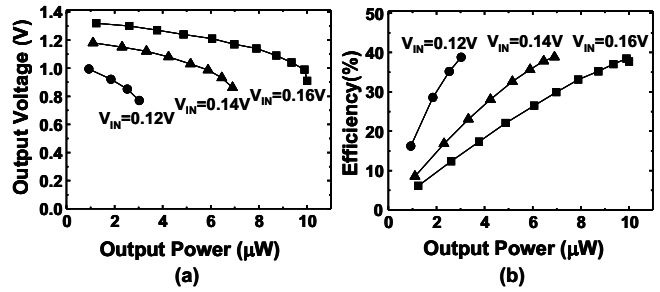


Fig.5. Measured dependence of (a) output voltage and (b) conversion efficiency on output power.

TABLE I

Performance comparison of fully integrated charge pump

| Ref.                | ISSCC'07 [3] | ISSCC'09 [4]     | CICC'10 [5] | This work      |
|---------------------|--------------|------------------|-------------|----------------|
| CMOS Process        | 350nm        | 350nm            | 65nm        | 65nm           |
| $V_{IN}$ (min)      | 1V           | 0.6V             | 0.18V       | 0.12V          |
| Efficiency          | 50%          | 70%              | N/A         | 38.8%          |
| External excitation | No           | Yes (2V battery) | No          | No (Dual-mode) |

V. Conclusion

We have demonstrated a 120-mV fully-integrated charge pump using novel dual-mode architecture. The dual-mode architecture achieves both low startup voltage and high conversion efficiency at the same time without using additional inductor/capacitor. It converts 120mV input to 770mV output with 38.8% conversion efficiency. To the best of our knowledge, it is the lowest operation voltage in CMOS charge pump circuit.

Acknowledgments

This work was carried out as a part of the Extremely Low Power (ELP) project supported by METI and NEDO.

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